













SN74AVCH1T45

SCES598E - JULY 2004-REVISED MARCH 2016

# SN74AVCH1T45 Single-Bit Dual-Supply Bus Transceiver With Configurable Level-Shifting, Voltage Translation, and 3-State Outputs

#### **Features**

- Available in the Texas Instruments NanoStar™ and NanoFree™ Packages
- Control Inputs (DIR) VIH and VIL Levels Are Referenced to V<sub>CCA</sub> Voltage
- Bus Hold on Data Inputs Eliminates the Need for External Pullup and Pulldown Resistors
- V<sub>CC</sub> Isolation
- Fully Configurable Dual-Rail Design
- I/Os Are 4.6-V Tolerant
- Ioff Supports Partial-Power-Down Mode Operation
- Typical Max Data Rates
  - 500 Mbps (1.8-V to 3.3-V Translation)
  - 320 Mbps (<1.8-V to 3.3-V Translation)
  - 320 Mbps (Translate to 2.5 V or 1.8 V)
  - 280 Mbps (Translate to 1.5 V)
  - 240 Mbps (Translate to 1.2 V)
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
  - Human-Body Model (A114-A): 2000 V
  - Machine Model (A115-A): 200 V
  - Charged-Device Model (C101): 1000 V

# 2 Applications

- Personal Electronics
- Industrial
- Enterprise
- **Telecommunications**

# 3 Description

The SN74AVCH1T45 is a single-bit noninverting bus transceiver that uses two separate configurable power-supply rails. The A port is designed to track V<sub>CCA</sub>, which accepts any supply voltage from 1.2 V to 3.6 V. The B port is designed to track V<sub>CCB</sub>, which also accepts any supply voltage from 1.2 V to 3.6 V. This allows for universal low-voltage bidirectional translation between any of the 1.2-V, 1.5-V, 1.8-V, 2.5-V, and 3.3-V voltage nodes.

The SN74AVCH1T45 is designed for asynchronous communication between two data buses. The device transmits data from either the A bus to the B bus, or from the B bus to the A bus, depending upon the logic level at the direction-control (DIR) input.

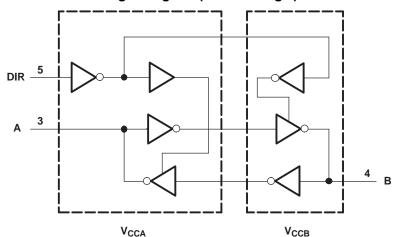
The SN74AVCH1T45 is designed so that the DIR input is referenced to V<sub>CCA</sub>.

### Device Information<sup>(1)</sup>

PART NUMBER	PACKAGE	BODY SIZE (NOM)		
	SC70 (6)	2.00 mm × 1.25 mm		
SN74AVCH1T45	SOT-23 (6)	2.90 mm × 1.60 mm		
	DSBGA (6)	1.50 mm × 0.90 mm		

(1) For all available packages, see the orderable addendum at the end of the data sheet.

#### Logic Diagram (Positive Logic)





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# 4 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

#### Changes from Revision D (January 2008) to Revision E

**Page** 

Added ESD Ratings table, Feature Description section, Device Functional Modes, Application and Implementation section, Power Supply Recommendations section, Layout section, Device and Documentation Support section, and 



## 5 Description (continued)

Active bus-hold circuitry holds unused or undriven inputs at a valid logic state. Use of pullup or pulldown resistors with the bus-hold circuitry is not recommended.

This device is fully specified for partial-power-down applications using I<sub>off</sub>. The I<sub>off</sub> circuitry disables the outputs, preventing damaging current backflow through the device.

The  $V_{CC}$  isolation feature ensures that if either  $V_{CCA}$  or  $V_{CCB}$  is at GND, then the outputs are in the high-impedance state. The bus-hold circuitry on the powered-up side always stays active.

NanoFree package technology is a major breakthrough in IC packaging concepts, using the die as the package.

# 6 Pin Configuration and Functions



#### Pin Functions

ı	PIN		DESCRIPTION			
NAME	NO.	1/0	DESCRIPTION			
Α	3	I/O	Input/output A. Referenced to V <sub>CCA</sub> .			
B 4 I/O		I/O	Input/output B. Referenced to V <sub>CCB</sub> .			
DIR	5	I	Direction control signal. Referenced to V <sub>CCA</sub> .			
$V_{CCA}$	1	_	A-port supply voltage. 1.2 V ≤ V <sub>CCA</sub> ≤ 3.6 V			
V <sub>CCB</sub> 6 —		_	B-port supply voltage. 1.2 V $\leq$ V <sub>CCB</sub> $\leq$ 3.6 V.			
GND	2	_	Ground			

Product Folder Links: SN74AVCH1T45



# **Specifications**

#### 7.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)(1)

		MIN	MAX	UNIT
Supply voltage	V <sub>CCA</sub> and V <sub>CCB</sub>	-0.5	4.6	V
	I/O ports (A port)	-0.5	4.6	
Input voltage <sup>(2)</sup>	I/O ports (B port)	-0.5	4.6	V
	Control inputs	-0.5	4.6	
Voltage applied to any output in the high-impedance or power-off	A port	-0.5	4.6	.,
state (2)	B port	-0.5	4.6	V
V-16-0-0-15-11-0-0-0-15-11-0-15-11-0-15-11-0-15-11-0-15-11-0-15-11-0-15-11-0-15-11-0-15-11-0-15-11-0-15-11-0-15	A port	-0.5	-0.5     4.6       -0.5     4.6       -0.5     4.6       -0.5     4.6       -0.5     4.6       -0.5     4.6	
Voltage applied to any output in the high or low state (2)(3)	B port	-0.5	V <sub>CCB</sub> + 0.5	V
Input clamp current	V <sub>I</sub> < 0		-50	mA
Output clamp current	V <sub>O</sub> < 0		-50	mA
Continuous output current			±50	mA
Continuous through current	V <sub>CCA</sub> , V <sub>CCB</sub> , or GND		±100	mA
Junction temperature, T <sub>J</sub>	•	-40	150	°C
Storage temperature, T <sub>stg</sub>		-65	150	°C

<sup>(1)</sup> Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under Recommended Operating Conditions. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

## 7.2 ESD Ratings

			VALUE	UNIT
		Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 <sup>(1)</sup>	±2000	
V <sub>(ESD)</sub>	Electrostatic discharge	Charged-device model (CDM), per JEDEC specification JESD22-C101 (2)	±1000	V
		Machine model, per A115-A	±200	

JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.

#### 7.3 Recommended Operating Conditions

see (1)(2)(3)(4)(5)

				MIN	MAX	UNIT
$V_{CCA}$	Supply voltage			1.2	3.6	V
$V_{CCB}$	Supply voltage			1.2	3.6	V
			$V_{CCI} = 1.2 \text{ V to } 1.95 \text{ V}$	$V_{CCI} \times 0.65$		
$V_{IH}$	High-level input voltage <sup>(1)</sup> Data	Data inputs <sup>(4)</sup>	$V_{CCI} = 1.95 \text{ V to } 2.7 \text{ V}$	1.6		V
			$V_{CCI} = 2.7 \text{ V to } 3.6 \text{ V}$	2	2	
			$V_{CCI} = 1.2 \text{ V to } 1.95 \text{ V}$		$V_{\rm CCI} \times 0.35$	
$V_{IL}$	Low-level input voltage (1)	Data inputs <sup>(4)</sup>	$V_{CCI}$ = 1.95 V to 2.7 V		0.7	V
			V <sub>CCI</sub> = 2.7 V to 3.6 V		0.8	
			$V_{CCI} = 1.2 \text{ V to } 1.95 \text{ V}$	$V_{CCA} \times 0.65$		
$V_{IH}$	H High-level input voltage DIR (referenced to	DIR (referenced to V <sub>CCA</sub> ) <sup>(5)</sup>	V <sub>CCI</sub> = 1.95 V to 2.7 V	1.6		V
		(Totolollosa to VCCA)	$V_{CCI} = 2.7 \text{ V to } 3.6 \text{ V}$	2		

 $V_{\text{CCI}}$  is the  $V_{\text{CC}}$  associated with the input port.

 $V_{\text{CCO}}$  is the  $V_{\text{CC}}$  associated with the output port.

All unused control inputs of the device must be held at V<sub>CCI</sub> or GND to ensure proper device operation.

For  $V_{CCI}$  values not specified in the data sheet,  $V_{IH}$  min =  $V_{CCI} \times 0.7$  V,  $V_{IL}$  max =  $V_{CCI} \times 0.3$  V.

For  $V_{CCI}$  values not specified in the data sheet,  $V_{IH}$  min =  $V_{CCA} \times 0.7$  V,  $V_{IL}$  max =  $V_{CCA} \times 0.3$  V. (5)

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The input voltage and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.

The output positive-voltage rating may be exceeded up to 4.6 V maximum if the output current rating is observed.

JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.



# **Recommended Operating Conditions (continued)**

see (1)(2)(3)(4)(5)

				MIN	MAX	UNIT		
			V <sub>CCI</sub> = 1.2 V to 1.95 V	V <sub>C</sub>	<sub>CCA</sub> × 0.35			
$V_{IL}$	Low-level input voltage	DIR (referenced to V <sub>CCA</sub> ) <sup>(5)</sup>	V <sub>CCI</sub> = 1.95 V to 2.7 V		0.7	V		
		(referenced to veca)	V <sub>CCI</sub> = 2.7 V to 3.6 V		0.8			
VI	Input voltage	Control Inputs (3)		0	3.6	V		
.,	Output voltage (2)	Active state		0	V <sub>cco</sub>	V		
Vo	Output voltage (-)	3-state		0 V <sub>CCO</sub> 0 3.6 -3 -6 -8	V			
			V <sub>CCO</sub> = 1.2 V		-3			
			$V_{CCO} = 1.4 \text{ V to } 1.6 \text{ V}$		-6			
I <sub>OH</sub>	High-level output current		V <sub>CCO</sub> = 1.65 V to 1.95 V		-8	mA		
			$V_{CCO} = 2.3 \text{ V to } 2.7 \text{ V}$	0 0 0	-9			
			$V_{CCO} = 3 \text{ V to } 3.6 \text{ V}$		V <sub>CCA</sub> × 0.35 0.7 0.8 3.6 V <sub>CCO</sub> 3.6 -3 -6 -8			
			V <sub>CCO</sub> = 1.2 V		3			
			$V_{CCO} = 1.4 \text{ V to } 1.6 \text{ V}$		6			
I <sub>OL</sub>	Low-level output current		$V_{CCO} = 1.65 \text{ V to } 1.95 \text{ V}$		8	mA		
			$V_{CCO} = 2.3 \text{ V to } 2.7 \text{ V}$		9			
			$V_{CCO} = 3 \text{ V to } 3.6 \text{ V}$		12			
Δt/Δν	Input transition rise or fall rate	e			5	ns/V		
T <sub>A</sub>	Operating free-air temperatur	re		-40	85	°C		

## 7.4 Thermal Information

	THERMAL METRIC <sup>(1)</sup>	DBV (SOT-23)	DCK (SC70)	YZP (DSBGA)	UNIT
		6 PINS	6 PINS	6 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance <sup>(2)</sup>	24.3	290.7	130	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	174.7	97	54	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	92.4	99.2	51	°C/W
$\Psi_{JT}$	Junction-to-top characterization parameter	61.1	2.1	1	°C/W
$\Psi_{JB}$	Junction-to-board characterization parameter	92	98.4	50	°C/W

For more information about traditional and new thermal metrics, see the Semiconductor and IC Package Thermal Metrics application report, SPRA953.

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<sup>(2)</sup> The package thermal impedance is calculated in accordance with JESD 51-7.



## 7.5 Electrical Characteristics

All typical limits apply over  $T_A = 25$ °C, and all maximum and minimum limits apply over  $T_A = -40$ °C to 85°C (unless otherwise noted). (1)(2)(3)(4)

	PARAMETER	TEST	CONDITIONS		MIN	TYP	MAX	UNIT
		$I_{OH} = -100 \mu A, V_I = V_{IH}$	$V_{CCA} = V_{CCB} = 1.2 \text{ V to}$	3.6 V	V <sub>CCO</sub> - 0.2 V			
		$I_{OH} = -3 \text{ mA}, V_I = V_{IH}$	$V_{CCA} = V_{CCB} = 1.2 \text{ V}$			0.95		
. ,	High-level output	$I_{OH} = -6 \text{ mA}, V_I = V_{IH}$	$V_{CCA} = V_{CCB} = 1.4 \text{ V}$		1.05			
V <sub>OH</sub>	voltage <sup>(1)</sup>	$I_{OH} = -8 \text{ mA}, V_I = V_{IH}$	$V_{CCA} = V_{CCB} = 1.65 \text{ V}$		1.2			V
		$I_{OH} = -9$ mA, $V_I = V_{IH}$	$V_{CCA} = V_{CCB} = 2.3 \text{ V}$		1.75			
		$I_{OH} = -12 \text{ mA}, V_I = V_{IH}$	$V_{CCA} = V_{CCB} = 3 \text{ V}$		2.3			
		$I_{OL} = 100 \mu A, V_I = V_{IL}$	$V_{CCA} = V_{CCB} = 1.2 \text{ V to}$	3.6 V			0.2	
		$I_{OL} = 3 \text{ mA}, V_I = V_{IL}$	$V_{CCA} = V_{CCB} = 1.2 \text{ V}$			0.15		
. ,	Low-level output	$I_{OL} = 6 \text{ mA}, V_I = V_{IL}$	$V_{CCA} = V_{CCB} = 1.4 \text{ V}$				0.35	V
$V_{OL}$	voltage	$I_{OL} = 8 \text{ mA}, V_{I} = V_{IL}$	V <sub>CCA</sub> = V <sub>CCB</sub> = 1.65 V				0.45	V
		$I_{OL} = 9 \text{ mA}, V_I = V_{IL}$	$V_{CCA} = V_{CCB} = 2.3 \text{ V}$				0.55	
		$I_{OL} = 12 \text{ mA}, V_I = V_{IL}$	$V_{CCA} = V_{CCB} = 3 \text{ V}$				0.7	
I <sub>I</sub>	Control Input (DIR)	V <sub>I</sub> = V <sub>CCA</sub> or GND	$V_{CCA} = V_{CCB} = 1.2 \text{ V to}$	3.6 V		±0.025	±1	μA
		V <sub>I</sub> = 0.42 V	$V_{CCA} = V_{CCB} = 1.2 \text{ V}$			25		
	Bus-hold low	V <sub>I</sub> = 0.49 V	$V_{CCA} = V_{CCB} = 1.4 \text{ V}$		15			
I <sub>BHL</sub>	sustaining	V <sub>I</sub> = 0.58 V	V <sub>CCA</sub> = V <sub>CCB</sub> = 1.65 V		25			μΑ
	current <sup>(5)</sup>	V <sub>I</sub> = 0.7 V	$V_{CCA} = V_{CCB} = 2.3 \text{ V}$		45			
		V <sub>I</sub> = 0.8 V	$V_{CCA} = V_{CCB} = 3.3 \text{ V}$		100			
		V <sub>I</sub> = 0.78 V	$V_{CCA} = V_{CCB} = 1.2 \text{ V}$			-25		
	Bus-hold high	V <sub>I</sub> = 0.91 V	$V_{CCA} = V_{CCB} = 1.4 \text{ V}$		-15			
I <sub>BHH</sub>	sustaining	V <sub>I</sub> = 1.07 V	V <sub>CCA</sub> = V <sub>CCB</sub> = 1.65 V		-25			μΑ
	current <sup>(6)</sup>	V <sub>I</sub> = 1.6 V	$V_{CCA} = V_{CCB} = 2.3 \text{ V}$		-45			
		V <sub>I</sub> = 2 V	$V_{CCA} = V_{CCB} = 3.3 \text{ V}$		-100			
			$V_{CCA} = V_{CCB} = 1.2 \text{ V}$			50		
	Bus-hold low		$V_{CCA} = V_{CCB} = 1.6 \text{ V}$		125			
I <sub>BHLO</sub>	overdrive	$V_I = 0$ to $V_{CC}$	$V_{CCA} = V_{CCB} = 1.95 \text{ V}$		200			μΑ
	current <sup>(3)</sup>		$V_{CCA} = V_{CCB} = 2.7 \text{ V}$		300			
			$V_{CCA} = V_{CCB} = 3.6 \text{ V}$		500			
			$V_{CCA} = V_{CCB} = 1.2 \text{ V}$			-50		
	Bus-hold high		$V_{CCA} = V_{CCB} = 1.6 \text{ V}$		-125			
I <sub>внно</sub>	overdrive	$V_I = 0$ to $V_{CC}$	V <sub>CCA</sub> = V <sub>CCB</sub> = 1.95 V		-200			μΑ
	current <sup>(4)</sup>		$V_{CCA} = V_{CCB} = 2.7 \text{ V}$		-300			
			$V_{CCA} = V_{CCB} = 3.6 \text{ V}$		-500			
	Input and output Power-off	V <sub>I</sub> = 0 V to 3.6 V,	V	A Port		±0.1	±5	
l <sub>off</sub>	Power-oπ leakge current	V <sub>O</sub> = 0 V to 3.6 V	$V_{CCA} = 0 \text{ V to } 3.6 \text{ V},$ $V_{CCB} = 0 \text{ V}$	3 Port		±0.1	±5	μA

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<sup>(3)</sup> 

 $V_{CCO}$  is the  $V_{CC}$  associated with the output port.  $V_{CCI}$  is the  $V_{CC}$  associated with the input port. An external driver must source at least  $I_{BHLO}$  to switch this node from low to high. An external driver must sink at least  $I_{BHHO}$  to switch this node from high to low. The bus-hold circuit can sink at least the minimum low sustaining current at  $V_{IL}$  max.  $I_{BHL}$  should be measured after lowering  $V_{IN}$  to GND and then raising it to  $V_{\text{IL}}\ \text{max}.$ 

The bus-hold circuit can source at least the minimum high sustaining current at  $V_{IH}$  min.  $I_{BHH}$  should be measured after raising  $V_{IN}$  to  $V_{\text{CC}}$  and then lowering it to  $V_{\text{IH}}$  min.



# **Electrical Characteristics (continued)**

All typical limits apply over  $T_A = 25^{\circ}C$ , and all maximum and minimum limits apply over  $T_A = -40^{\circ}C$  to 85°C (unless otherwise noted). (1)(2)(3)(4)

	PARAMETER	TEST (	CONDITIONS		MIN	TYP	MAX	UNIT
	Off-state output	$V_I = V_{CCI}$ or GND,	V <sub>CCA</sub> = 0 V, V <sub>CCB</sub> = 3.6 V	A Port		±0.5	±5	
I <sub>OZ</sub>	current <sup>(7)</sup>	$V_{O} = V_{CCO}$ or GND	$V_{CCA} = 3.6 \text{ V},$ $V_{CCB} = 0 \text{ V}$	B port		±0.5	±5	μΑ
			$V_{CCA} = V_{CCB} = 1.2$	2 V to 3.6 V			10	
$I_{CCA}$	Supply current A port	$V_I = V_{CCI}$ or GND, $I_O = 0$	$V_{CCA} = 0 \text{ V}, V_{CCB}$	= 3.6 V			-2	μΑ
	port		$V_{CCA} = 3.6 \text{ V}, V_{CC}$	<sub>CB</sub> = 0 V			10 10	
			$V_{CCA} = V_{CCB} = 1.2$	2 V to 3.6 V			10	
$I_{CCB}$	Supply current B port	$V_I = V_{CCI}$ or GND, $I_O = 0$	$V_{CCA} = 0 \text{ V}, V_{CCB} = 3.6 \text{ V}$				10	μΑ
	port		$V_{CCA} = 3.6 \text{ V}, V_{CCB} = 0 \text{ V}$				-2	
I <sub>CCA</sub> + I <sub>CCB</sub>	Combined supply current	$V_I = V_{CCI}$ or GND, $I_O = 0$	$V_{CCA} = V_{CCB} = 1.2$	2 V to 3.6 V			20	μΑ
C <sub>i</sub>	Input capacitance control pin (DIR)	V <sub>I</sub> = 3.3 V or GND	$V_{CCA} = V_{CCB} = 3.3$	3 V		2.5		pF
C <sub>io</sub>	Input and output capacitance A or B port	$V_O = 3.3 \text{ V or GND}$	$V_{CCA} = V_{CCB} = 3.3$	3 V		6		pF

<sup>(7)</sup> For I/O ports, the parameter  $I_{\mbox{\scriptsize OZ}}$  includes the input leakage current.

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# 7.6 Switching Characteristics, $V_{CCA}$ = 1.2 V

 $T_A = 25^{\circ}C$  (see Figure 11).

	PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT	
				V <sub>CCB</sub> = 1.2 V		3.3			
	Propagation delay time:			V <sub>CCB</sub> = 1.5 V		2.7			
PLH, PHL	low-to-high-level output and	Α	В	V <sub>CCB</sub> = 1.8 V		2.4		ns	
PHL	high-to-low level output			V <sub>CCB</sub> = 2.5 V		2.3			
				V <sub>CCB</sub> = 3.3 V		2.4			
				V <sub>CCB</sub> = 1.2 V		3.3			
	Propagation delay time:			V <sub>CCB</sub> = 1.5 V		3.1			
PLH, PHL	low-to-high-level output and	В	Α	V <sub>CCB</sub> = 1.8 V		2.9		ns	
PHL	high-to-low level output			V <sub>CCB</sub> = 2.5 V		2.8			
				V <sub>CCB</sub> = 3.3 V		2.7			
				V <sub>CCB</sub> = 1.2 V		5.1			
	Enable time: to high level <sup>(1)</sup> and to low level <sup>(1)</sup>			V <sub>CCB</sub> = 1.5 V		5.2		ns	
t <sub>PZH</sub> , t <sub>PZL</sub>		DIR	Α	V <sub>CCB</sub> = 1.8 V		5.3			
				V <sub>CCB</sub> = 2.5 V		5.2			
				V <sub>CCB</sub> = 3.3 V		3.7			
				V <sub>CCB</sub> = 1.2 V		5.3			
	Enable time:			V <sub>CCB</sub> = 1.5 V		4.3			
PZH <sup>,</sup> PZL	to high level (1) and	DIR	В	V <sub>CCB</sub> = 1.8 V		4		ns	
PZL	to low level <sup>(1)</sup>			V <sub>CCB</sub> = 2.5 V		3.3			
				V <sub>CCB</sub> = 3.3 V		3.7			
				V <sub>CCB</sub> = 1.2 V		8.5			
	Disable time:			V <sub>CCB</sub> = 1.5 V		6.9			
PHZ, PLZ	from high level and	DIR	Α	V <sub>CCB</sub> = 1.8 V		6.4		ns	
PLZ	from low level			V <sub>CCB</sub> = 2.5 V		5.5			
				V <sub>CCB</sub> = 3.3 V		6.1			
				V <sub>CCB</sub> = 1.2 V		8.3			
	Disable time:		В	V <sub>CCB</sub> = 1.5 V		7.8		ns	
PHZ,	from high level and from low level	DIR		V <sub>CCB</sub> = 1.8 V		7.7			
PLZ				V <sub>CCB</sub> = 2.5 V		7.5			
				V <sub>CCB</sub> = 3.3 V		5.9			

<sup>(1)</sup> The enable time is a calculated value, derived using the formula shown in *Enable Times*.



# 7.7 Switching Characteristics, $V_{CCA}$ = 1.5 V ± 0.1 V

All typical limits apply over  $T_A = 25$ °C, and all maximum and minimum limits apply over  $T_A = -40$ °C to 85°C (unless otherwise noted) (see Figure 11).

	PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
				V <sub>CCB</sub> = 1.2 V		2.9		
	Propagation delay time:			V <sub>CCB</sub> = 1.5 V ± 0.1 V	0.7		5.6	ns
t <sub>PLH</sub> , t <sub>PHL</sub>	low-to-high-level output and	Α	В	V <sub>CCB</sub> = 1.8 V ± 0.15 V	0.6		4.2	
PHL	high-to-low level output			V <sub>CCB</sub> = 2.5 V ± 0.2 V	0.5		4.2	
				$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$	0.5		3.8	
				V <sub>CCB</sub> = 1.2 V		2.6		
	Propagation delay time:			V <sub>CCB</sub> = 1.5 V ± 0.1 V	0.6		5.5	
t <sub>PLH</sub> , t <sub>PHL</sub>	low-to-high-level output and	В	Α	V <sub>CCB</sub> = 1.8 V ± 0.15 V	0.4		5.3	ns
THL	high-to-low level output			$V_{CCB} = 2.5 \text{ V} \pm 0.2 \text{ V}$	0.3		4.9	
				$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$	0.3		4.8	
				V <sub>CCB</sub> = 1.2 V		3.8		
	Enable time:			V <sub>CCB</sub> = 1.5 V ± 0.1 V	1.6		6.7	5.8 ns
t <sub>PZH</sub> , t <sub>PZL</sub>	to high level <sup>(1)</sup> and to low level <sup>(1)</sup>	DIR	A	$V_{CCB} = 1.8 \text{ V} \pm 0.15 \text{ V}$	1.5		6.8	
*PZL				$V_{CCB} = 2.5 \text{ V} \pm 0.2 \text{ V}$	0.3		6.9	
				$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$	0.9		6.9	
				V <sub>CCB</sub> = 1.2 V		5.1		
	Enable time:			V <sub>CCB</sub> = 1.5 V ± 0.1 V	1.8		8.1	
$t_{PZH}$ , $t_{PZL}$	to high level <sup>(1)</sup> and	DIR	В	$V_{CCB} = 1.8 \text{ V} \pm 0.15 \text{ V}$	1.6		7.1	ns
17ZL	to low level <sup>(1)</sup>			$V_{CCB} = 2.5 \text{ V} \pm 0.2 \text{ V}$	1.1		4.7	
				$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$	1.4		4.5	
				V <sub>CCB</sub> = 1.2 V		7.7		
	Disable time:			V <sub>CCB</sub> = 1.5 V ± 0.1 V			13.6	
$t_{PHZ}$ , $t_{PLZ}$	from high level and	DIR	Α	$V_{CCB} = 1.8 \text{ V} \pm 0.15 \text{ V}$			12.4	ns
PLZ	from low level			$V_{CCB} = 2.5 \text{ V} \pm 0.2 \text{ V}$			9.6	
				$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$			9.3	
				V <sub>CCB</sub> = 1.2 V		6.7		
	Disable time:			V <sub>CCB</sub> = 1.5 V ± 0.1 V			12.3	
$t_{PHZ}$ , $t_{PLZ}$	from high level and	rel and DIR	В	V <sub>CCB</sub> = 1.8 V ± 0.15 V			12	ns
PLZ	from low level			V <sub>CCB</sub> = 2.5 V ± 0.2 V			11.1	
				V <sub>CCB</sub> = 3.3 V ± 0.3 V			10.7	

<sup>(1)</sup> The enable time is a calculated value, derived using the formula shown in *Enable Times*.

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# 7.8 Switching Characteristics, $V_{CCA}$ = 1.8 V ± 0.15 V

All typical limits apply over  $T_A = 25^{\circ}C$ , and all maximum and minimum limits apply over  $T_A = -40^{\circ}C$  to 85°C (unless otherwise noted) (see Figure 11).

	PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT	
				V <sub>CCB</sub> = 1.2 V		2.8			
	Propagation delay time:			V <sub>CCB</sub> = 1.5 V ± 0.1 V	0.6		5.3		
t <sub>PLH</sub> , t <sub>PHL</sub>	low-to-high-level output and	Α	В	V <sub>CCB</sub> = 1.8 V ± 0.15 V	0.5		5	ns	
PHL	high-to-low level output			V <sub>CCB</sub> = 2.5 V ± 0.2 V	0.4		3.9		
				$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$	0.4		3.4		
				V <sub>CCB</sub> = 1.2 V		2.3			
	Propagation delay time:			V <sub>CCB</sub> = 1.5 V ± 0.1 V	0.5		5.2		
t <sub>PLH</sub> , t <sub>PHL</sub>	low-to-high-level output and	В	Α	$V_{CCB} = 1.8 \text{ V} \pm 0.15 \text{ V}$	0.4		5	ns	
PHL	high-to-low level output			V <sub>CCB</sub> = 2.5 V ± 0.2 V	0.3		4.6		
				$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$	0.2		4.4		
				V <sub>CCB</sub> = 1.2 V		3.8			
	Enable time:		А	V <sub>CCB</sub> = 1.5 V ± 0.1 V	1.6		5.9	ns	
$t_{PZH}$ , $t_{PZL}$	to high level <sup>(1)</sup> and to low level <sup>(1)</sup>	DIR		V <sub>CCB</sub> = 1.8 V ± 0.15 V	1.6		5.9		
*PZL				$V_{CCB} = 2.5 \text{ V} \pm 0.2 \text{ V}$	1.6		5.9		
				$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$	0.5		6		
				V <sub>CCB</sub> = 1.2 V		5			
	Enable time:		В	V <sub>CCB</sub> = 1.5 V ± 0.1 V	1.8		7.7	ns	
$t_{PZH}$ , $t_{PZL}$	to high level <sup>(1)</sup> and	DIR		$V_{CCB} = 1.8 \text{ V} \pm 0.15 \text{ V}$	1.4		6.8		
17ZL	to low level <sup>(1)</sup>			$V_{CCB} = 2.5 \text{ V} \pm 0.2 \text{ V}$	1		4.4		
				$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$	1.4		4.3	 	
				V <sub>CCB</sub> = 1.2 V		7.3			
	Disable time:			$V_{CCB} = 1.5 \text{ V} \pm 0.1 \text{ V}$			12.9		
$t_{PHZ}$ , $t_{PLZ}$	from high level and	DIR	Α	$V_{CCB} = 1.8 \text{ V} \pm 0.15 \text{ V}$			11.8	ns	
PLZ	from low level			$V_{CCB} = 2.5 \text{ V} \pm 0.2 \text{ V}$			9		
				$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$			8.7		
				V <sub>CCB</sub> = 1.2 V		6.5			
	Disable time:			$V_{CCB} = 1.5 \text{ V} \pm 0.1 \text{ V}$			11.2	ns	
$t_{PHZ}$ , $t_{PLZ}$	from high level and	DIR	В	$V_{CCB} = 1.8 \text{ V} \pm 0.15 \text{ V}$			10.9		
712	from low level			$V_{CCB} = 2.5 \text{ V} \pm 0.2 \text{ V}$			9.8		
				$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$			9.4		

<sup>(1)</sup> The enable time is a calculated value, derived using the formula shown in *Enable Times*.



# 7.9 Switching Characteristics, $V_{CCA}$ = 2.5 V ± 0.2 V

All typical limits apply over  $T_A = 25^{\circ}C$ , and all maximum and minimum limits apply over  $T_A = -40^{\circ}C$  to 85°C (unless otherwise noted) (see Figure 11).

PARAMETER		FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT	
				V <sub>CCB</sub> = 1.2 V		2.6			
	Propagation delay time:		В	V <sub>CCB</sub> = 1.5 V ± 0.1 V	0.5		4.9		
t <sub>PLH</sub> ,	low-to-high-level output and	Α		V <sub>CCB</sub> = 1.8 V ± 0.15 V	0.4		4.6	ns	
t <sub>PHL</sub>	high-to-low level output			V <sub>CCB</sub> = 2.5 V ± 0.2 V	0.3		3.4		
				$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$	0.3		3		
				V <sub>CCB</sub> = 1.2 V		2.2			
	Propagation delay time:			V <sub>CCB</sub> = 1.5 V ± 0.1 V	0.4		4.2		
t <sub>PLH</sub> , t <sub>PHL</sub>	low-to-high-level output and	В	Α	$V_{CCB} = 1.8 \text{ V} \pm 0.15 \text{ V}$	0.3		3.8	ns	
THL	high-to-low level output			$V_{CCB} = 2.5 \text{ V} \pm 0.2 \text{ V}$	0.2		3.4		
				$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$	0.2		3.3		
				V <sub>CCB</sub> = 1.2 V		2.8		ns	
	Enable time: to high level <sup>(1)</sup> and to low level <sup>(1)</sup>			$V_{CCB} = 1.5 \text{ V} \pm 0.1 \text{ V}$	0.3		3.8		
$t_{PZH}$ , $t_{PZL}$		DIR	Α	$V_{CCB} = 1.8 \text{ V} \pm 0.15 \text{ V}$	0.8		3.8		
17ZL				$V_{CCB} = 2.5 \text{ V} \pm 0.2 \text{ V}$	0.4		3.8		
				$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$	0.5		3.8		
				V <sub>CCB</sub> = 1.2 V		4.9			
	Enable time:		В	V <sub>CCB</sub> = 1.5 V ± 0.1 V	2		7.6	ns	
$t_{PZH}$ , $t_{PZL}$	to high level <sup>(1)</sup> and	DIR		$V_{CCB} = 1.8 \text{ V} \pm 0.15 \text{ V}$	1.5		6.5		
17ZL	to low level <sup>(1)</sup>			$V_{CCB} = 2.5 \text{ V} \pm 0.2 \text{ V}$	0.6		4.1		
				$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$	1		4		
				V <sub>CCB</sub> = 1.2 V		7.1			
	Disable time:			V <sub>CCB</sub> = 1.5 V ± 0.1 V			11.8		
$t_{PHZ}$ , $t_{PLZ}$	from high level and	DIR	Α	$V_{CCB} = 1.8 \text{ V} \pm 0.15 \text{ V}$			10.3	ns	
PLZ	from low level			$V_{CCB} = 2.5 \text{ V} \pm 0.2 \text{ V}$			7.5		
				$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$			7.3		
				V <sub>CCB</sub> = 1.2 V		5.4			
	Disable time:			V <sub>CCB</sub> = 1.5 V ± 0.1 V			8.6	ns	
$t_{PHZ}$ , $t_{PLZ}$	from high level and	DIR	В	V <sub>CCB</sub> = 1.8 V ± 0.15 V			8.1		
PLZ	from low level			V <sub>CCB</sub> = 2.5 V ± 0.2 V			7		
				$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$			6.6		

<sup>(1)</sup> The enable time is a calculated value, derived using the formula shown in *Enable Times*.

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# 7.10 Switching Characteristics, $V_{CCA}$ = 3.3 V ± 0.3 V

All typical limits apply over  $T_A = 25$ °C, and all maximum and minimum limits apply over  $T_A = -40$ °C to 85°C (unless otherwise noted) (see Figure 11).

	PARAMETER		TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT	
				V <sub>CCB</sub> = 1.2 V		2.6			
	Propagation delay time:		В	V <sub>CCB</sub> = 1.5 V ± 0.1 V	0.4		4.7	ns	
t <sub>PLH</sub> ,	low-to-high-level output and	Α		V <sub>CCB</sub> = 1.8 V ± 0.15 V	0.3		4.4		
PHL	high-to-low level output			$V_{CCB} = 2.5 \text{ V} \pm 0.2 \text{ V}$	0.2		3.3		
				$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$	0.2		2.8		
				V <sub>CCB</sub> = 1.2 V		2.2			
	Propagation delay time:			V <sub>CCB</sub> = 1.5 V ± 0.1 V	0.4		3.8		
PLH <sup>,</sup> PHL	low-to-high-level output and	В	Α	V <sub>CCB</sub> = 1.8 V ± 0.15 V	0.3		3.4	ns	
PHL	high-to-low level output			$V_{CCB} = 2.5 \text{ V} \pm 0.2 \text{ V}$	0.2		3		
				$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$	0.1		2.8		
				V <sub>CCB</sub> = 1.2 V		3.1			
t <sub>PZH</sub> , t <sub>PZL</sub>	Enable time: to high level <sup>(1)</sup> and to low level <sup>(1)</sup>		А	V <sub>CCB</sub> = 1.5 V ± 0.1 V	1.3		4.3	ns	
		DIR		V <sub>CCB</sub> = 1.8 V ± 0.15 V	1.3		4.3		
				$V_{CCB} = 2.5 \text{ V} \pm 0.2 \text{ V}$	1.3		4.3		
				V <sub>CCB</sub> = 3.3 V ± 0.3 V	1.3		4.3		
				V <sub>CCB</sub> = 1.2 V		4			
	Enable time:			V <sub>CCB</sub> = 1.5 V ± 0.1 V	0.7		7.4	ns	
PZH <sup>,</sup> PZL	to high level <sup>(1)</sup> and	DIR	В	V <sub>CCB</sub> = 1.8 V ± 0.15 V	0.6		6.5		
PZL	to low level <sup>(1)</sup>			V <sub>CCB</sub> = 2.5 V ± 0.2 V	0.7		4		
				$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$	1.5		3.9		
				V <sub>CCB</sub> = 1.2 V		6.2			
	Disable time:			$V_{CCB} = 1.5 \text{ V} \pm 0.1 \text{ V}$			11.2		
PHZ <sup>,</sup> PLZ	from high level and	DIR	Α	$V_{CCB} = 1.8 \text{ V} \pm 0.15 \text{ V}$			9.9	ns	
PLZ	from low level			$V_{CCB} = 2.5 \text{ V} \pm 0.2 \text{ V}$			7		
				$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$			6.7		
				V <sub>CCB</sub> = 1.2 V		5.7			
	Disable time:			V <sub>CCB</sub> = 1.5 V ± 0.1 V			8.9	ns	
PHZ <sup>,</sup> PLZ	from high level and	DIR	В	V <sub>CCB</sub> = 1.8 V ± 0.15 V			8.5		
PLZ	from low level			$V_{CCB} = 2.5 \text{ V} \pm 0.2 \text{ V}$			7.2		
				$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$			6.8		

<sup>(1)</sup> The enable time is a calculated value, derived using the formula shown in *Enable Times*.

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# 7.11 Operating Characteristics

 $T_{\Lambda} = 25^{\circ}C$ 

	PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST C	ONDITIONS	ТҮР	UNIT	
					$V_{CCA} = V_{CCB} = 1.2 \text{ V}$	3		
				$C_1 = 0 pF$	$V_{CCA} = V_{CCB} = 1.5 \text{ V}$	3		
		Α	В	f = 10 MHz,	$V_{CCA} = V_{CCB} = 1.8 \text{ V}$	3	pF	
C				$t_r = t_f = 1 \text{ ns}$	$V_{CCA} = V_{CCB} = 2.5 \text{ V}$	3		
	Power dissipation capacitance per transceiver <sup>(1)</sup>				$V_{CCA} = V_{CCB} = 3.3 \text{ V}$	4		
$C_{pdA}$	port A				$V_{CCA} = V_{CCB} = 1.2 \text{ V}$	14		
			A	$C_L = 0 \text{ pF},$ f = 10  MHz, $t_r = t_f = 1 \text{ ns}$	$V_{CCA} = V_{CCB} = 1.5 \text{ V}$	14	pF	
		В			$V_{CCA} = V_{CCB} = 1.8 \text{ V}$	14		
					$V_{CCA} = V_{CCB} = 2.5 \text{ V}$	15		
					$V_{CCA} = V_{CCB} = 3.3 \text{ V}$	16		
			В		$V_{CCA} = V_{CCB} = 1.2 \text{ V}$	14		
				$C_L = 0 pF,$	$V_{CCA} = V_{CCB} = 1.5 \text{ V}$	14	pF	
		Α		f = 10 MHz,	$V_{CCA} = V_{CCB} = 1.8 \text{ V}$	14		
				$t_r = t_f = 1 \text{ ns}$	$V_{CCA} = V_{CCB} = 2.5 \text{ V}$	15		
0	Power dissipation capacitance				$V_{CCA} = V_{CCB} = 3.3 \text{ V}$	16		
C <sub>pdB</sub>	per transceiver <sup>(1)</sup> port B				$V_{CCA} = V_{CCB} = 1.2 \text{ V}$	3		
	·			$C_L = 0 pF,$	$V_{CCA} = V_{CCB} = 1.5 \text{ V}$	3	pF	
		В	Α	f = 10 MHz,	$V_{CCA} = V_{CCB} = 1.8 \text{ V}$	3		
				$t_r = t_f = 1 \text{ ns}$	$V_{CCA} = V_{CCB} = 2.5 \text{ V}$	3		
					$V_{CCA} = V_{CCB} = 3.3 \text{ V}$	4		

<sup>(1)</sup> See CMOS Power Consumption and Cpd Calculation, SCAA035.

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## 7.12 Typical Characteristics

 $T_A = 25^{\circ}C$ 

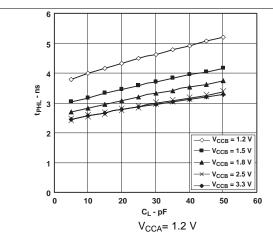


Figure 1. Typical Propagation Delay (A to B) vs Load Capacitance

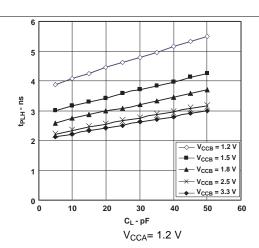


Figure 2. Typical Propagation Delay (A to B) vs Load Capacitance

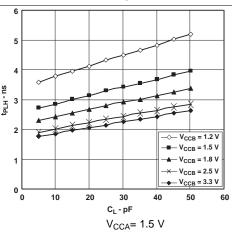


Figure 3. Typical Propagation Delay (A to B) vs Load Capacitance

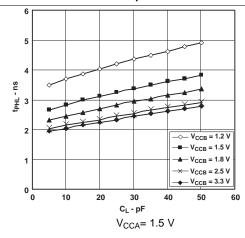


Figure 4. Typical Propagation Delay (A to B) vs Load Capacitance

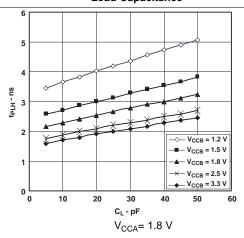


Figure 5. Typical Propagation Delay (A to B) vs Load Capacitance

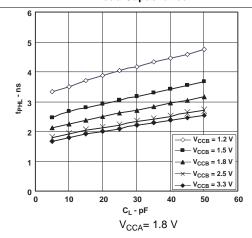


Figure 6. Typical Propagation Delay (A to B) vs Load Capacitance



# **Typical Characteristics (continued)**

T<sub>A</sub>= 25°C

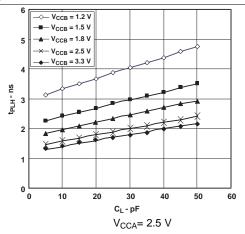


Figure 7. Typical Propagation Delay (A to B) vs Load Capacitance

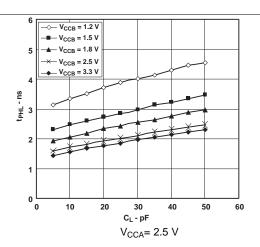


Figure 8. Typical Propagation Delay (A to B) vs Load Capacitance

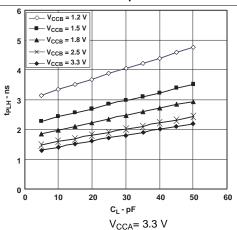


Figure 9. Typical Propagation Delay (A to B) vs Load Capacitance

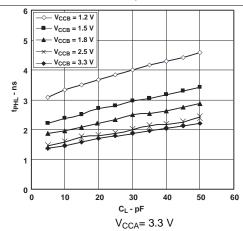
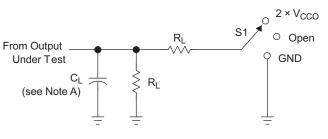


Figure 10. Typical Propagation Delay (A to B) vs Load Capacitance

 $V_{CCA}$ 



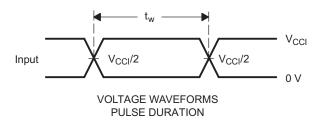
### 8 Parameter Measurement Information

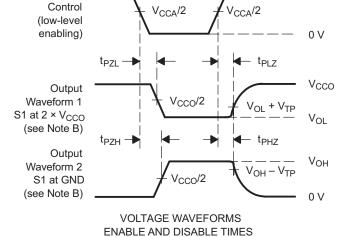


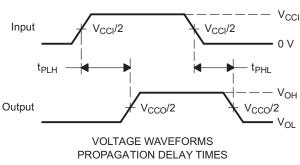
TEST	S1
t <sub>pd</sub>	Open
t <sub>PLZ</sub> /t <sub>PZL</sub>	2 × V <sub>CCO</sub>
t <sub>PHZ</sub> /t <sub>PZH</sub>	GND

LOAD CIRCUIT

V <sub>CCO</sub>	C <sub>L</sub>	R <sub>L</sub>	V <sub>TP</sub>
1.2 V	15 pF	2 kW	0.1 V
1.5 V ± 0.1 V	15 pF	2 kW	0.1 V
1.8 V ± 0.15 V	15 pF	2 kW	0.15 V
$2.5 V \pm 0.2 V$	15 pF	2 kW	0.15 V
$3.3 \text{ V} \pm 0.3 \text{ V}$	15 pF	2 kW	0.3 V







NOTES: A. C<sub>I</sub> includes probe and jig capacitance.

B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.

Output

- C. All input pulses are supplied by generators having the following characteristics: PRR 10 MHz, Z<sub>O</sub> = 50 W, dv/dt ≥ 1 V/ns.
- D. The outputs are measured one at a time, with one transition per measurement.
- E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
- F. t<sub>PZL</sub> and t<sub>PZH</sub> are the same as t<sub>en</sub>.
- G.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .
- H.  $V_{CCI}$  is the  $V_{CC}$  associated with the input port.
- I.  $V_{CCO}$  is the  $V_{CC}$  associated with the output port.

Figure 11. Load Circuit and Voltage Waveforms

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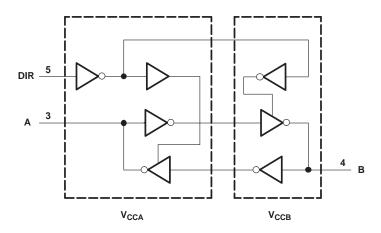


#### 9 Detailed Description

#### 9.1 Overview

The SN74AVCH1T45 is a single-bit, dual-supply, noninverting voltage level translator. Pins A and DIR are referenced to  $V_{CCA}$ , while pin B is referenced to  $V_{CCB}$ . Both the A port and B port can accept I/O voltages ranging from 1.2 V to 3.6 V. The high on DIR allows data transmission from Port A to Port B and a low on DIR allows data transmission from Port B to Port A. See applications report, *AVC Logic Family Technology and Applications* (SCLA015), for more information.

#### 9.2 Functional Block Diagram



### 9.3 Feature Description

#### 9.3.1 Fully Configurable Dual-Rail Design

Both  $V_{CCA}$  and  $V_{CCB}$  can be supplied at any voltage from 1.2 V to 3.6 V, making the device suitable for translating between any of the voltage nodes (1.2 V, 1.8 V, 2.5 V and 3.3 V).

#### 9.3.2 Supports High-Speed Translation

SN74AVCH1T45 can support high data rate applications, which can be calculated from the maximum propagation delay. This is also dependent on output load. For example, a 1.8-V to 3.3-V conversion yields a maximum data rate of 500 Mbps.

#### 9.3.3 Partial-Power-Down Mode Operation

l<sub>off</sub> circuitry disables the outputs, preventing damaging current backflow through the SN74AVCH1T45 when it is powered down. This can occur in applications where subsections of a system are powered down (partial-power-down) to reduce power consumption.

## 9.3.4 Active Bus-Hold Circuitry

Active bus-hold circuitry holds unused or undriven data inputs at a valid logic state, which helps with board space savings and reduced component costs. Use of pullup or pulldown resistors with the bus-hold circuitry is not recommended. See applications report, *Bus-Hold Circuit* (SCLA015), for more information.

#### 9.3.5 V<sub>CC</sub> Isolation

The  $V_{CC}$  isolation feature ensures that if either  $V_{CCA}$  or  $V_{CCB}$  are at GND (or < 0.4 V), both ports will be in a high-impedance state ( $I_{OZ}$  as shown in *Electrical Characteristics*). This prevents false logic levels from being presented to either bus.



#### 9.4 Device Functional Modes

Table 1 lists the functional modes of the SN74AVCH1T45.

**Table 1. Function Table** 

DIR	OPERATION
L	B data to A bus
Н	A data to B bus

## 10 Application and Implementation

#### **NOTE**

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

## 10.1 Application Information

The SN74AVCH1T45 device can be used in level-translation applications for interfacing devices or systems operating at different interface voltages with one another. The maximum data rate can be up to 500 Mbps when device translate signal from 1.8 V to 3.3 V.

# 10.2 Typical Applications

#### 10.2.1 Unidirectional Logic Level-Shifting Application

Figure 12 shows an example of the SN74AVCH1T45 being used in a unidirectional logic level-shifting application.

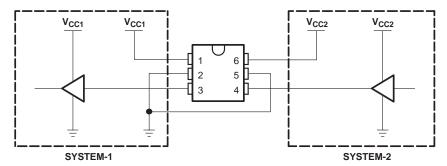


Figure 12. Unidirectional Logic Level-Shifting Application Diagram

Table 2. Data Transmission: SYSTEM-1 and SYSTEM-2

PIN	NAME	FUNCTION	DESCRIPTION
1	$V_{CCA}$	V <sub>CC1</sub>	SYSTEM-1 supply voltage (1.2 V to 3.6 V)
2	GND	GND	Device GND
3	A	OUT	Output level depends on V <sub>CC1</sub> voltage.
4	В	IN	Input threshold value depends on V <sub>CC2</sub> voltage.
5	DIR	DIR	GND (low level) determines B-port to A-port direction.
6	V <sub>CCB</sub>	$V_{CC2}$	SYSTEM-2 supply voltage (1.2 V to 3.6 V)

Product Folder Links: SN74AVCH1T45



#### 10.2.1.1 Design Requirements

For this design example, use the parameters listed in Table 3.

**Table 3. Design Parameters** 

DESIGN PARAMETERS	EXAMPLE VALUES
Input voltage	1.2 V to 3.6 V
Output voltage	1.2 V to 3.6 V

#### 10.2.1.2 Detailed Design Procedure

To begin the design process, determine the following:

- · Input voltage range
  - Use the supply voltage of the device that is driving the SN74AVCH1T45 device to determine the input voltage range. For a valid logic-high, the value must exceed the V<sub>IH</sub> of the input port. For a valid logic low the value must be less than the V<sub>IL</sub> of the input port.
- Output voltage range
  - Use the supply voltage of the device that the SN74AVCH1T45 device is driving to determine the output voltage range.

#### 10.2.1.3 Application Curve

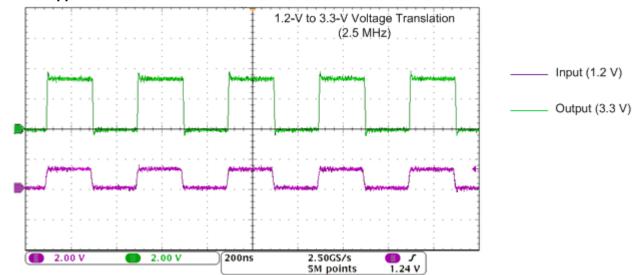


Figure 13. Translation Up (1.2 V to 3.3 V) at 2.5 MHz

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#### 10.2.2 Bidirectional Logic Level-Shifting Application

Figure 14 shows the SN74AVCH1T45 being used in a bidirectional logic level-shifting application. Because the SN74AVCH1T45 does not have an output-enable (OE) pin, the system designer should take precautions to avoid bus contention between SYSTEM-1 and SYSTEM-2 when changing directions.

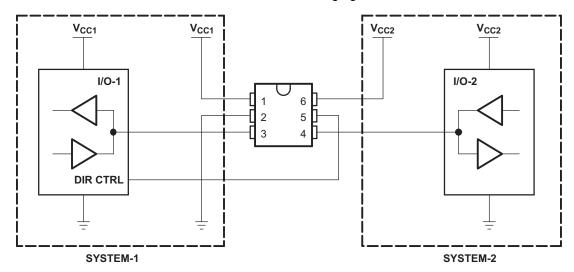


Figure 14. Bidirectional Logic Level-Shifting Application Diagram

The following table shows data transmission from SYSTEM-1 to SYSTEM-2 and then from SYSTEM-2 to SYSTEM-1.

Table 4. Data Transmission: SYSTEM-1 and SYSTEM-2

STATE	DIR CTRL	I/O-1	I/O-2	DESCRIPTION
1	Н	Out	In	SYSTEM-1 data to SYSTEM-2
2	Н	Hi-Z	Hi-Z	SYSTEM-2 is getting ready to send data to SYSTEM-1. I/O-1 and I/O-2 are disabled.
3	L	Hi-Z	Hi-Z	DIR bit is flipped. I/O-1 and I/O-2 still are disabled.
4	L	In	Out	SYSTEM-2 data to SYSTEM-1

#### 10.2.2.1 Design Requirements

Refer to Design Requirements found in Unidirectional Logic Level-Shifting Application.

#### 10.2.2.2 Detailed Design Procedure

#### 10.2.2.2.1 Enable Times

Calculate the enable times for the SN74AVCH1T45 using the following formulas:

- $t_{PZH}$  (DIR to A) =  $t_{PLZ}$ (DIR to B) +  $t_{PLH}$  (B to A)
- $t_{PZI}$  (DIR to A) =  $t_{PHZ}$ (DIR to B) +  $t_{PHI}$  (B to A)
- $t_{PZH}$  (DIR to B) =  $t_{PLZ}$ (DIR to A) +  $t_{PLH}$  (A to B)
- $t_{PZL}$  (DIR to B) =  $t_{PHZ}$ (DIR to A) +  $t_{PHL}$  (A to B)

In a bidirectional application, these enable times provide the maximum delay from the time the DIR bit is switched until an output is expected. For example, if the SN74AVCH1T45 initially is transmitting from A to B, then the DIR bit is switched; the B port of the device must be disabled before presenting it with an input. After the B port has been disabled, an input signal applied to it appears on the corresponding A port after the specified propagation delay.



#### 10.2.2.3 Application Curve

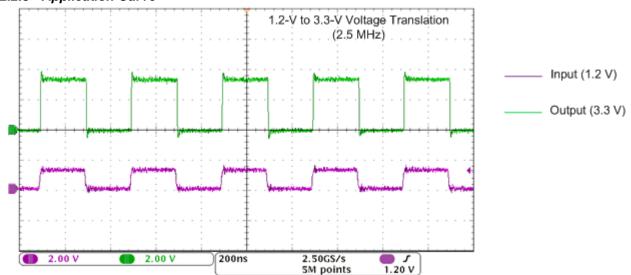


Figure 15. Translation Up (1.2 V to 3.3 V) at 2.5 MHz

# 11 Power Supply Recommendations

A proper power-up sequence must be followed to avoid excessive supply current, bus contention, oscillations, or other anomalies. To guard against such power-up problems, take the following precautions:

- 1. Connect ground before any supply voltage is applied.
- 2. Power up V<sub>CCA</sub>.
- 3.  $V_{CCB}$  can be ramped up along with or after  $V_{CCA}$ .

Table 5. Typical Total Static Power Consumption ( $I_{CCA} + I_{CCB}$ )

V		UNIT					
V <sub>CCB</sub>	0 V	1.2 V	1.5 V	1.8 V	2.5 V	3.3 V	UNII
0 V	0	<0.5	<0.5	<0.5	<0.5	<0.5	
1.2 V	<0.5	<1	<1	<1	<1	1	
1.5 V	<0.5	<1	<1	<1	<1	1	
1.8 V	<0.5	<1	<1	<1	<1	<1	μΑ
2.5 V	<0.5	1	<1	<1	<1	<1	
3.3 V	<0.5	1	<1	<1	<1	<1	

Product Folder Links: SN74AVCH1T45



# 12 Layout

# 12.1 Layout Guidelines

To ensure reliability of the device, TI recommends following common printed-circuit board layout guidelines.

- · Bypass capacitors should be used on power supplies.
- · Short trace lengths should be used to avoid excessive loading.
- Placing pads on the signal paths for loading capacitors or pullup resistors to help adjust rise and fall times of signals depending on the system requirements.

## 12.2 Layout Example



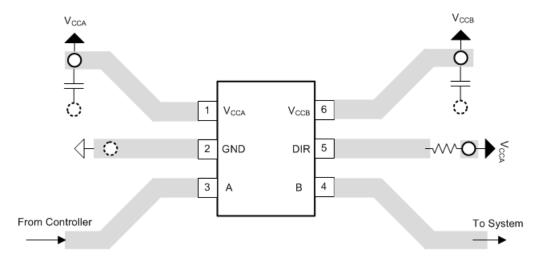


Figure 16. PCB Layout Example



# 13 Device and Documentation Support

## 13.1 Documentation Support

#### 13.1.1 Related Documentation

For related documentation see the following:

- Designing with SN74LVCXT245 and SN74LVCHXT245 Family of Direction Controlled Voltage Translators/Level-Shifters, SLVA746
- Bus-Hold Circuit, SCLA015
- AVC Logic Family Technology and Applications, SCEA006

#### 13.2 Community Resources

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's Terms of Use.

TI E2E™ Online Community TI's Engineer-to-Engineer (E2E) Community. Created to foster collaboration among engineers. At e2e.ti.com, you can ask questions, share knowledge, explore ideas and help solve problems with fellow engineers.

**Design Support** *TI's Design Support* Quickly find helpful E2E forums along with design support tools and contact information for technical support.

#### 13.3 Trademarks

NanoStar, NanoFree, E2E are trademarks of Texas Instruments. All other trademarks are the property of their respective owners.

### 13.4 Electrostatic Discharge Caution



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

#### 13.5 Glossary

SLYZ022 — TI Glossary.

This glossary lists and explains terms, acronyms, and definitions.

# 14 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

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25-Oct-2016

#### **PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish (6)	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
74AVCH1T45DBVRE4	ACTIVE	SOT-23	DBV	6	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	(ET1F ~ ET1R)	Samples
74AVCH1T45DBVRG4	ACTIVE	SOT-23	DBV	6	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	(ET1F ~ ET1R)	Samples
74AVCH1T45DBVTG4	ACTIVE	SOT-23	DBV	6	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	(ET1F ~ ET1R)	Samples
74AVCH1T45DCKRE4	ACTIVE	SC70	DCK	6	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	(TFF ~ TFR)	Samples
74AVCH1T45DCKRG4	ACTIVE	SC70	DCK	6	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	(TFF ~ TFR)	Samples
74AVCH1T45DCKTG4	ACTIVE	SC70	DCK	6	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	(TFF ~ TFR)	Samples
SN74AVCH1T45DBVR	ACTIVE	SOT-23	DBV	6	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	(ET1F ~ ET1R)	Samples
SN74AVCH1T45DBVT	ACTIVE	SOT-23	DBV	6	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	(ET1F ~ ET1R)	Samples
SN74AVCH1T45DCKR	ACTIVE	SC70	DCK	6	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	(TFF ~ TFR)	Samples
SN74AVCH1T45DCKT	ACTIVE	SC70	DCK	6	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	(TFF ~ TFR)	Samples
SN74AVCH1T45YZPR	ACTIVE	DSBGA	YZP	6	3000	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM	-40 to 85	(TE2 ~ TE7 ~ TEN)	Samples

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

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<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.



# PACKAGE OPTION ADDENDUM

25-Oct-2016

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above. **Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead/Ball Finish Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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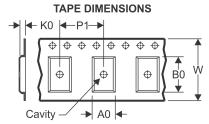
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

**PACKAGE MATERIALS INFORMATION** 

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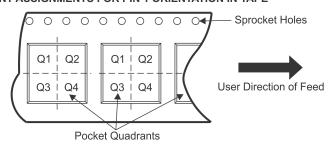
# TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

## QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AVCH1T45DBVR	SOT-23	DBV	6	3000	180.0	8.4	3.23	3.17	1.37	4.0	8.0	Q3
SN74AVCH1T45DBVT	SOT-23	DBV	6	250	180.0	8.4	3.23	3.17	1.37	4.0	8.0	Q3
SN74AVCH1T45DCKR	SC70	DCK	6	3000	180.0	8.4	2.41	2.41	1.2	4.0	8.0	Q3
SN74AVCH1T45DCKT	SC70	DCK	6	250	180.0	8.4	2.41	2.41	1.2	4.0	8.0	Q3
SN74AVCH1T45YZPR	DSBGA	YZP	6	3000	178.0	9.2	1.02	1.52	0.63	4.0	8.0	Q1

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\*All dimensions are nominal

All differentiations are normal											
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)				
SN74AVCH1T45DBVR	SOT-23	DBV	6	3000	202.0	201.0	28.0				
SN74AVCH1T45DBVT	SOT-23	DBV	6	250	202.0	201.0	28.0				
SN74AVCH1T45DCKR	SC70	DCK	6	3000	202.0	201.0	28.0				
SN74AVCH1T45DCKT	SC70	DCK	6	250	202.0	201.0	28.0				
SN74AVCH1T45YZPR	DSBGA	YZP	6	3000	220.0	220.0	35.0				

# DBV (R-PDSO-G6)

# PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
- D. Leads 1,2,3 may be wider than leads 4,5,6 for package orientation.
- Falls within JEDEC MO-178 Variation AB, except minimum lead width.



# DBV (R-PDSO-G6)

# PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
- D. Publication IPC-7351 is recommended for alternate designs.
- E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.



# DCK (R-PDSO-G6)

# PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
- D. Falls within JEDEC MO-203 variation AB.



# DCK (R-PDSO-G6)

# PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
- D. Publication IPC-7351 is recommended for alternate designs.
- E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.





DIE SIZE BALL GRID ARRAY



#### NOTES:

NanoFree Is a trademark of Texas Instruments.

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

  2. This drawing is subject to change without notice.
- 3. NanoFree<sup>™</sup> package configuration.



DIE SIZE BALL GRID ARRAY



NOTES: (continued)

4. Final dimensions may vary due to manufacturing tolerance considerations and also routing constraints. For more information, see Texas Instruments literature number SBVA017 (www.ti.com/lit/sbva017).



DIE SIZE BALL GRID ARRAY



NOTES: (continued)

5. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release.



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